

注記 NOTES:
 1.材質 MATERIAL
 ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
 GLASS FILLED, UL94V-0
 アクチュエータ: ポリアミド樹脂
 黒色、ガラス充填、UL94HB
 ACTUATOR: POLYAMIDE
 BLACK GLASS FILLED, UL94HB
 ターミナル: 燐青銅 (t=0.12)
 TERMINAL: PHOSPHOR BRONZE (t=0.12)
 金具: 燐青銅 (t=0.15)
 NAIL: PHOSPHOR BRONZE (t=0.15)
 2.めっき仕様 PLATING
 ターミナル TERMINAL
 接点部: 金めっき 0.1μm以上
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
 半田付け部: 金めっき
 SOLDER TAIL AREA: GOLD
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 金具 NAIL
 錫めっき 1.0μm以上
 TIN PLATING 1.0 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 3.平坦度は、0.1ミリ以下とする。
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.
 4.ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT
 5.本製品は502598-**91の端子材料変更品である。
 THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-**91.

14.4	16.95	15	17.4	502598-5193	51
12.6	15.15	13.2	15.6	502598-4593	45
11.4	13.95	12.0	14.4	502598-4193	41
10.8	13.35	11.4	13.8	502598-3993	39
9	11.55	9.6	12	502598-3393	33
7.8	10.35	8.4	10.8	502598-2993	29
7.2	9.75	7.8	10.2	502598-2793	27
6.6	9.15	7.2	9.6	502598-2593	25
6	8.55	6.6	9	502598-2393	23
4.2	6.75	4.8	7.2	502598-1793	17
3.6	6.15	4.2	6.6	502598-1593	15
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-**21

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差			
10 UNDER 未満		±0.2	
10 OVER 以上	30 UNDER 未満	±0.25	
30 OVER 以上		±0.3	
ANGLE 角度		±1°	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS	SCALE	CURRENT REV DESC:
mm	NTS	
GENERAL TOLERANCES (UNLESS SPECIFIED)		
ANGULAR TOL	±	°
4 PLACES	±	
3 PLACES	±	
2 PLACES	±	
1 PLACE	±	
0 PLACES	±	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		
THIRD ANGLE PROJECTION		
DRAWING	SERIES	MATERIAL NUMBER
A3-SIZE	502598	SEE TABLE
CUSTOMER		
GENERAL MARKET		
SHEET NUMBER		
1 OF 2		

EC NO: 704374
 DRWN: KYHWANG 2022/04/25
 CHK'D: SMARUYAMA 2022/05/09
 APPR: YNAITO 2022/05/09

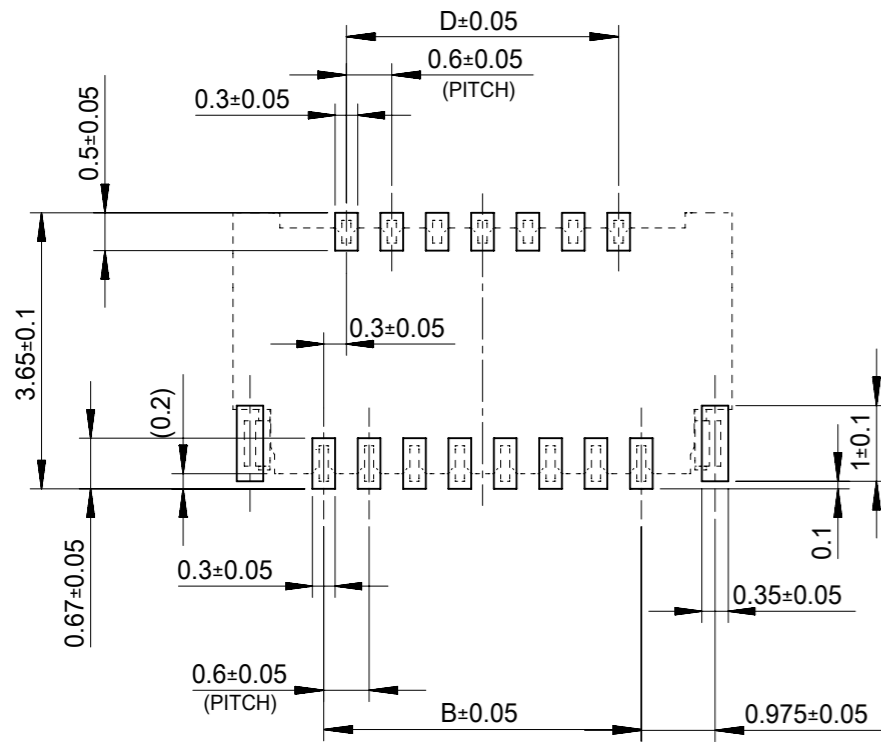
INITIAL REVISION:
 DRWN: KMIYAHARA 2012/07/18
 APPR: KMORIKAWA 2012/08/01

molex

0.3 FPC CONN. BACK FLIP HOUSING ASSY

PRODUCT CUSTOMER DRAWING

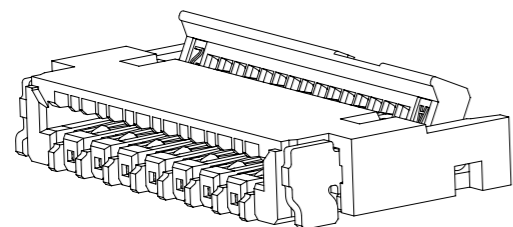
DOCUMENT NUMBER: SD-502598-003
 DOC TYPE: PSD
 DOC PART: 001
 REVISION: C



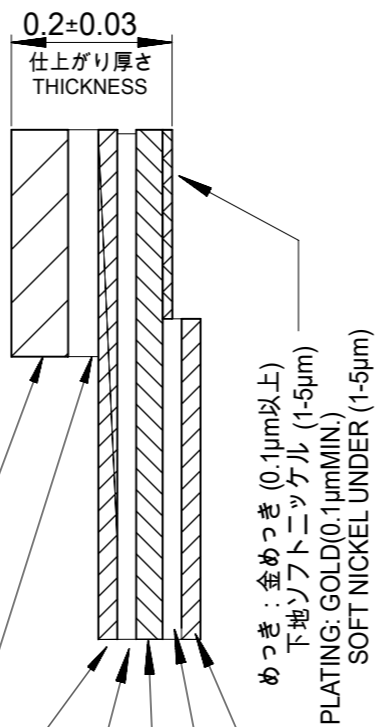
推奨基板寸法

RECOMMENDED P.W.B. PATTERN LAYOUT

マスク厚 : 100 μ m
 マスク開口率 : 100%
 SCREEN THICKNESS : 100 μ m
 SCREEN OPEN RATIO : 100%



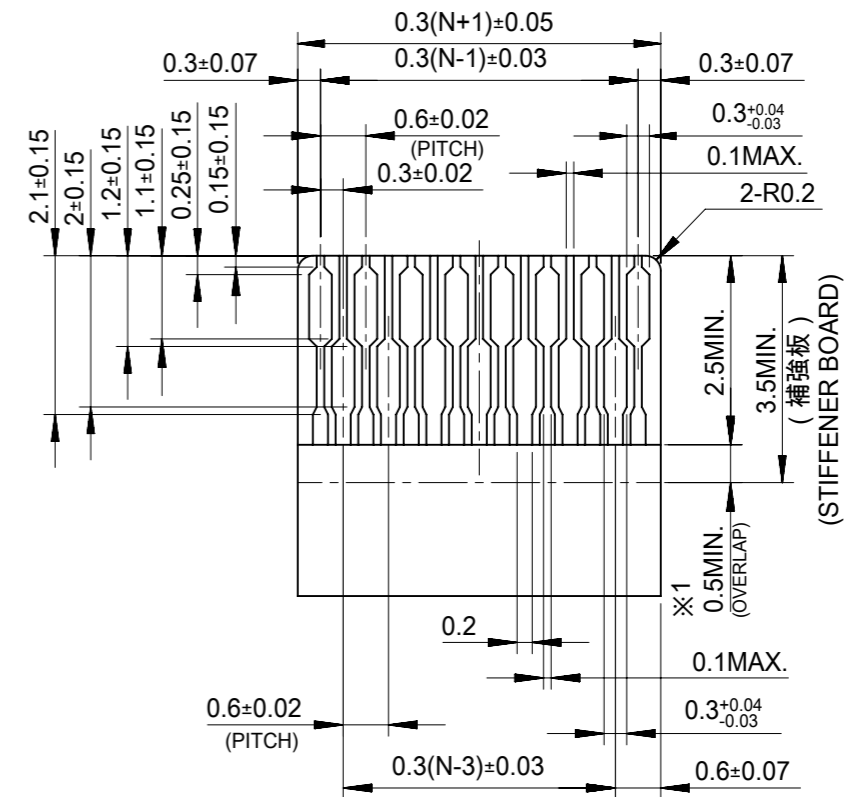
ISO VIEW (参考)



補強板 : ポリイミド
 REINFORCE BOARD: POLYIMIDE
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 ベースフィルム : ポリイミド (25 μ m)
 BASE FILM: POLYIMIDE(25 μ m)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 導体部 : 銅箔 (35 μ m)
 COPPER FOIL (35 μ m)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 カバーレイ : ポリイミド (25 μ m)
 COVER FILM: POLYIMIDE(25 μ m)

FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD PATING
 RECOMMENDED DIMENSION

(仕上がり厚さ : 0.2 \pm 0.03)
 (THICKNESS:0.2 \pm 0.03)

N : 極数
 N:CIRCUITS

FPCについて :

抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED MATERIAL:
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN
 ELECTRICAL CONTINUITY.

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE
		mm NTS
10 UNDER 未満	± 0.2	ANGULAR TOL \pm °
10 OVER 以上	30 UNDER 未満	4 PLACES \pm
	± 0.25	3 PLACES \pm
		2 PLACES \pm
30 OVER 以上	± 0.3	1 PLACE \pm
		0 PLACES \pm
ANGLE 角度	$\pm 1^\circ$	

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DIMENSION UNITS: mm SCALE: NTS

CURRENT REV DESC:

EC NO: 704374
 DRWN: KYHWANG 2022/04/25
 CHK'D: SMARUYAMA 2022/05/09
 APPR: YNAITO 2022/05/09

INITIAL REVISION:
 DRWN: KMIYAHARA 2012/07/18
 APPR: KMORIKAWA 2012/08/01

THIRD ANGLE PROJECTION

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

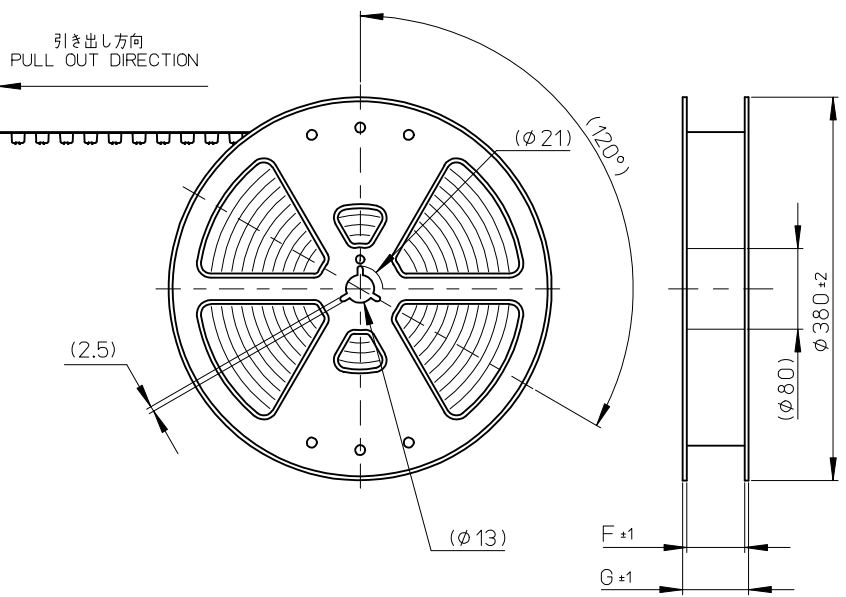
DRAWING: A3-SIZE SERIES: 502598 MATERIAL NUMBER: SEE SHEET 1 CUSTOMER: GENERAL MARKET SHEET NUMBER: 2 OF 2

molex

0.3 FPC CONN. BACK FLIP HOUSING ASSY

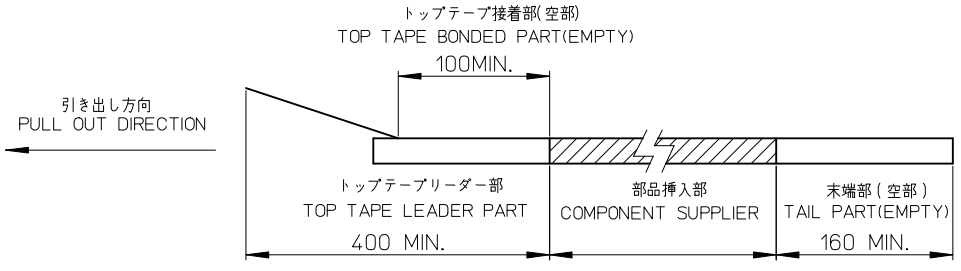
PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: SD-502598-003 DOC TYPE: PSD DOC PART: 001 REVISION: C



注記)
NOTES

1. 製品番号502598-**-21の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 502598-**-21 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: ポリエチレンテレフタレート (PET)、他
TOP TAPE : POLYETHYLENE TELEPHTHALATE (PET), OTHERS
リール: ポリスチレン (PS)
REEL: POLYSTYRENE (PS)

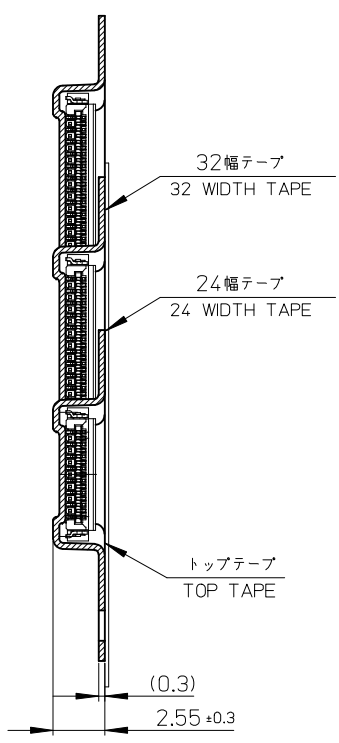
6. ELV及RoHS適合品
ELV AND RoHS COMPLIANT
7. 本製品は502598-**-91の端子材料変更品である。
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-**-91.

REVISED EC NO: J2014-0146 DRWN:KNAGUMO 2013/07/25 CHKD:KAKAHASHI 2013/08/30 APPR:YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**-21 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2012/08/01	molex MATERIAL NO. SEE TABLE DOCUMENT NO. SD-502598-004 SHEET NO. 1 OF 2			
ANGULAR ±1 °		SIZE A3						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

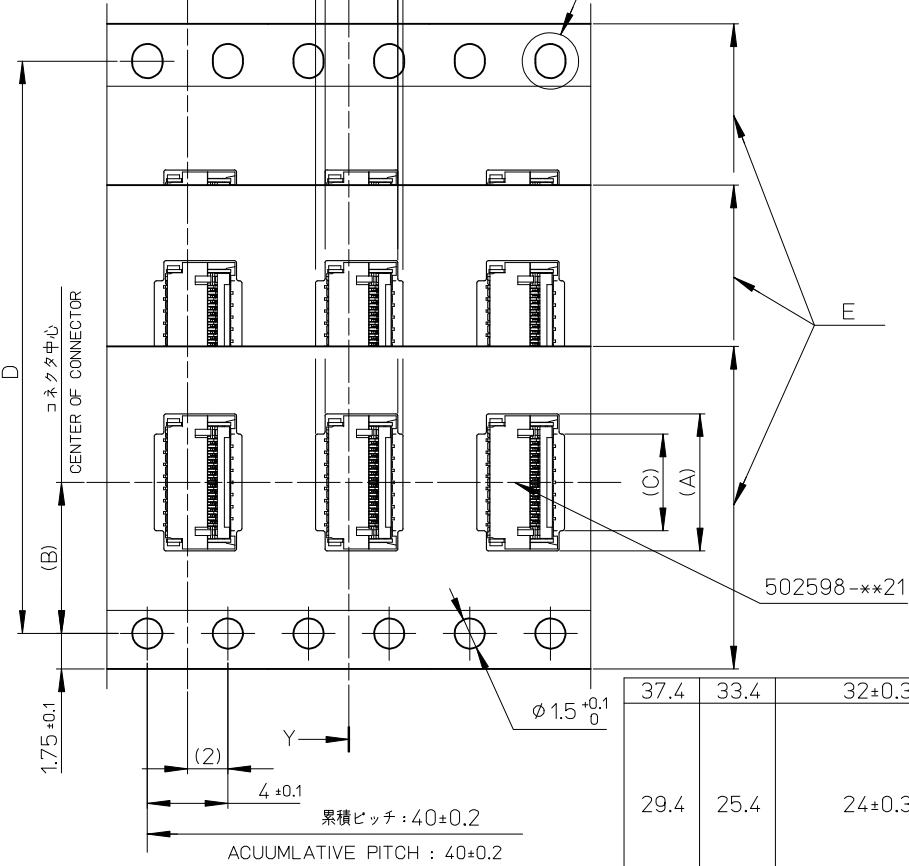
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION

Y
8 ± 0.1
(PITCH)
(2.43)
(4.34)
(3.61)



断面 Y-Y
SECTION Y-Y



コネクタ中心
CENTER OF CONNECTOR
(B)
1.75 ± 0.1
(2)
4 ± 0.1
累積ピッチ : 40 ± 0.2
ACUUMLATIVE PITCH : 40 ± 0.2
φ 1.5^{+0.1}₀

37.4	33.4	32 ± 0.3	28.4	15.7	14.2	17.6	502598-5193	51
29.4	25.4	24 ± 0.3	--	13.9	11.5	15.8	502598-4593	45
				12.7		14.6	502598-4193	41
				12.1		14	502598-3993	39
				10.3		12.2	502598-3393	33
				9.1		11	502598-2993	29
				8.5		10.4	502598-2793	27
				7.9		9.8	502598-2593	25
21.4	17.4	16 ± 0.3	--	7.3	7.5	9.2	502598-2393	23
				5.5		7.4	502598-1793	17
				4.9		6.8	502598-1593	15
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2014-0146 DRWN: KAGUMO 2013/07/25 CHKD: TAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**-21 SERIES)			
		10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2012/08/01				
REV	DESCRIPTION	ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE TABLE	DOCUMENT NO. SD-502598-004	SHEET NO. 2 OF 2		
B		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2